CM1408-04DE

4-Channel LCD and Camera EMI Filter Array with ESD Protection

ON Semiconductor®

http://onsemi.com

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WDFN8
DE SUFFIX
CASE 511BE

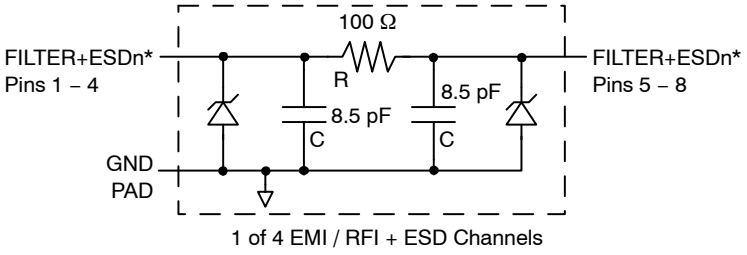
Features

- Four Channels of EMI Filtering with Integrated ESD Protection
- Pi−Style EMI Filters in a Capacitor−Resistor−Capacitor (C−R−C) Network
- ±15 kV ESD Protection on Each Channel (IEC 61000−4−2 Level 4, Contact Discharge)
- ±30 kV ESD Protection on Each Channel (HBM)
- Greater than −35 dB Attenuation (Typical) at 1 GHz
- WDFN Packaging with 0.5 mm Lead Pitch:
  - 8−Lead WDFN, 2.0 mm x 2.0 mm
- Increased Robustness Against Vertical Impacts During Manufacturing Process
- These Devices are Pb−Free and are RoHS Compliant

Applications

- LCD and Camera Data Lines in Mobile Handsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computers
- Wireless Handsets
- Handheld PCs/PDAs
- LCD and Camera Modules

BLOCK DIAGRAM



*See Package/Pinout Diagrams for expanded pin information.

MARKING DIAGRAM

N08 4E = CM1408−04DE

ORDERING INFORMATION

Device	Package	Shipping†
CM1408−04DE	WDFN−8 (Pb−Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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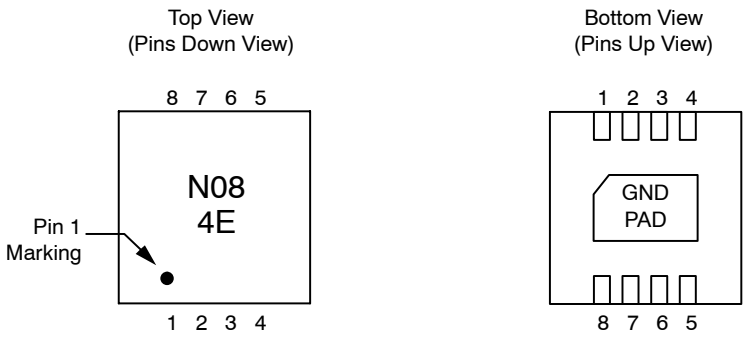
PACKAGE / PINOUT DIAGRAMS



8 Lead WDFN Package

Table 1. PIN DESCRIPTIONS

Device Pin(s)	Name	Description		Device Pin(s)	Name	Description
1	FILTER1	Filter + ESD Channel 1		8	FILTER1	Filter + ESD Channel 1
2	FILTER2	Filter + ESD Channel 2		7	FILTER2	Filter + ESD Channel 2
3	FILTER3	Filter + ESD Channel 3		6	FILTER3	Filter + ESD Channel 3
4	FILTER4	Filter + ESD Channel 4		5	FILTER4	Filter + ESD Channel 4
GND PAD	GND	Device Ground				

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	−65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature Range	−40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
R	Resistance		80	100	120	Ω
C_{TOTAL}	Total Channel Capacitance	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC	14	17	22	pF
C	Capacitance C	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC		8.5		pF
V_{DIODE}	Standoff Voltage	I_{DIODE} = 10 μA		6.0		V
I_{LEAK}	Diode Leakage Current (reverse bias)	V_{DIODE} = 3.3 V		0.1	1.0	μA
V_{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	 I_{LOAD} = 10 mA I_{LOAD} = −10 mA	 5.6 −1.5	 6.8 −0.8	 9.0 −0.4	V
V_{ESD}	In−system ESD Withstand Voltage a) Human Body Model, MIL−STD−883, Method 3015 b) Contact Discharge per IEC 61000−4−2 Level 4	(Notes 2 and 3)	 30 15			kV
R_{DYN}	Dynamic Resistance Positive Negative			 2.3 0.9		Ω
f_C	Cut−off Frequency Z_{SOURCE} = 50 Ω, Z_{LOAD} = 50 Ω	Channel R = 100 Ω, Channel C_{SINGLE} = 8.5 pF		 200		MHz

1. T_A = 25°C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.
3. These parameters are guaranteed by design and characterization.

PERFORMANCE INFORMATION

Typical Filter Performance (T_A = 25°C, DC Bias = 0 V, 50 Ω Environment)

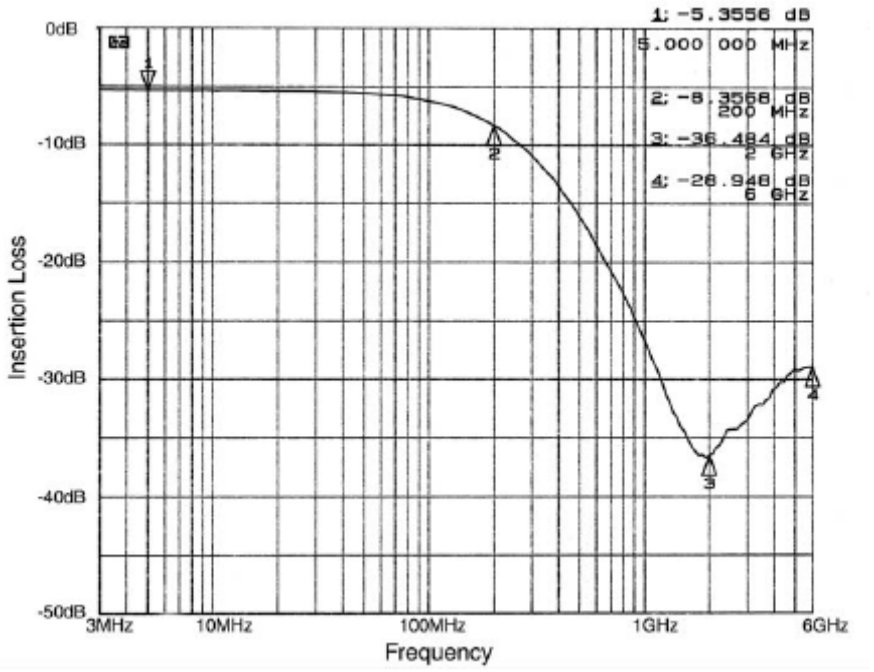


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND)

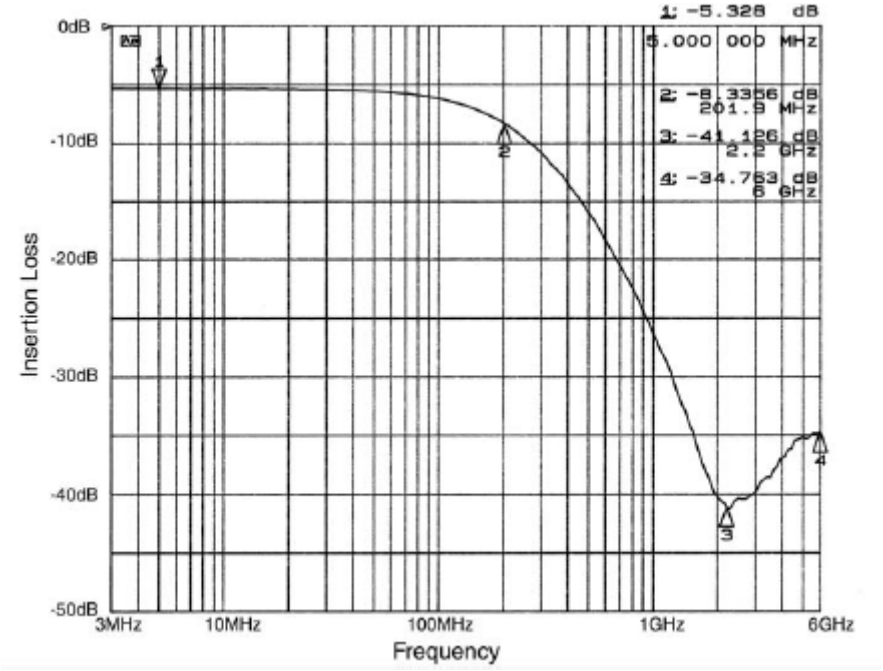


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance (T_A = 25°C, DC Bias = 0 V, 50 Ω Environment)

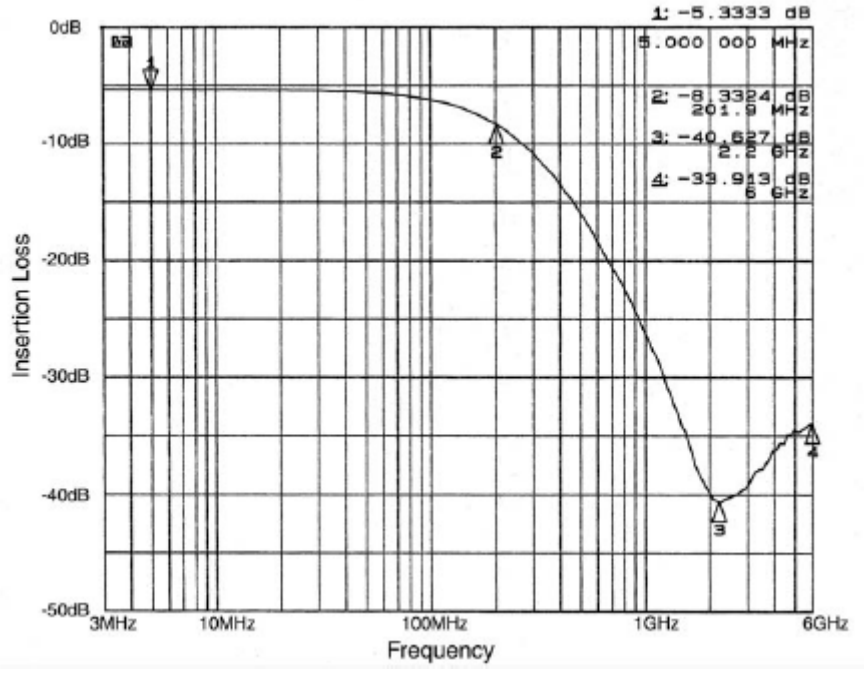


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND)

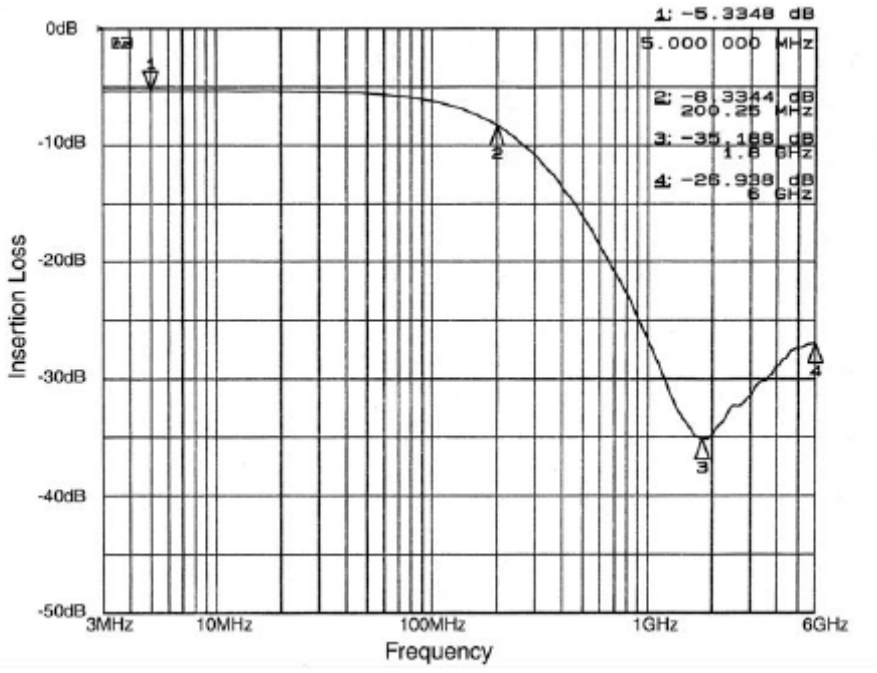


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

PERFORMANCE INFORMATION (Cont'd)

Typical Diode Capacitance vs. Input Voltage

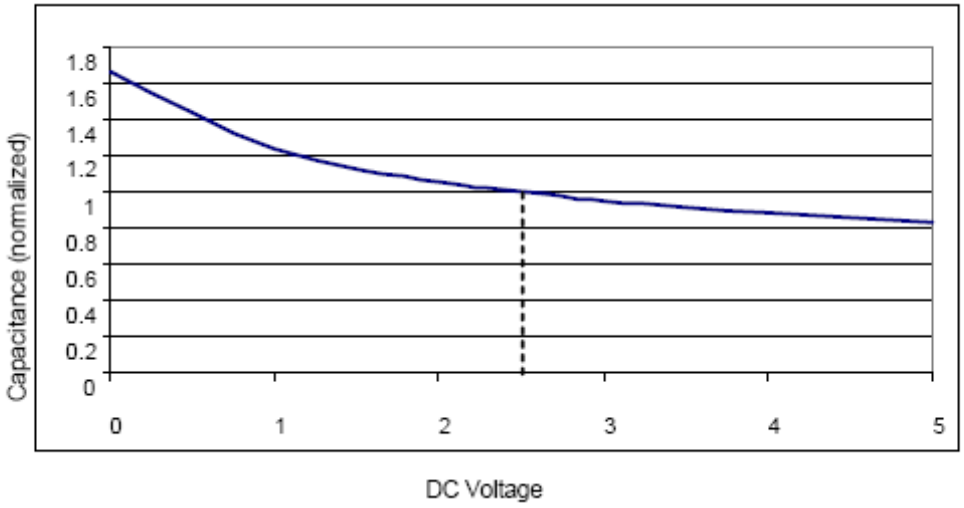
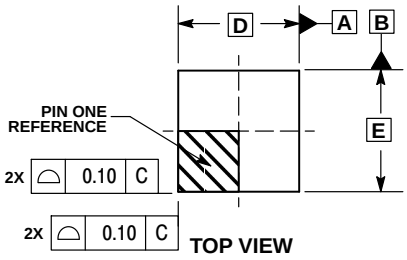


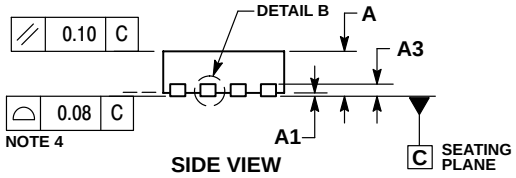
Figure 5. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5 VDC and 25°C)

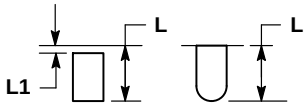
WDFN8 2x2, 0.5P
CASE 511BE
ISSUE A

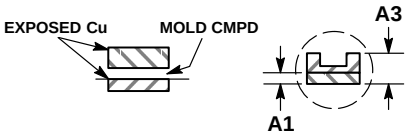
DATE 27 MAY 2011

SCALE 2:1



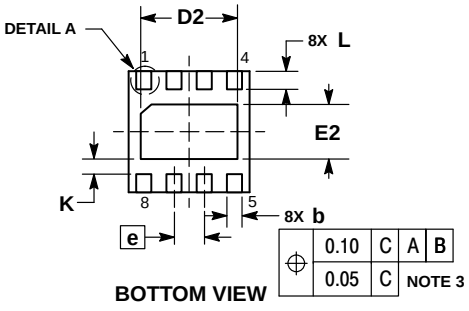




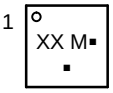


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.50	1.70
E	2.00 BSC	
E2	0.80	1.00
e	0.50 BSC	
K	0.25 REF	
L	0.20	0.40
L1	−−−	0.15



GENERIC MARKING DIAGRAM*

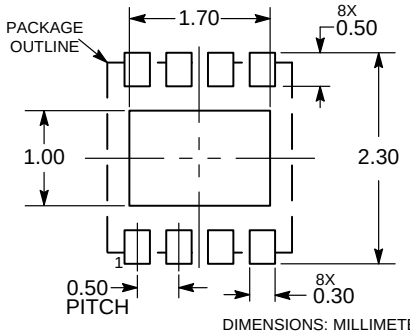


XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**WDFN8, 2X2, 0.5P**		**PAGE 1 OF 1**

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